

Layer	Stack up	Description	Impedance ID	Base Thickness	Finish Thickness	Mask Thickness	Type	εr	Notes-1	
		Soldermask				0.020	SolderMask	4.100	10	
1		Foil 1, 2, 3		0.012	0.035		Foil		0	
2		VT47-1080		0.075	0.075		PREPREG	4.000		
		Foil		0.009	0.032		Foil		0	
		VT47-106		0.053	0.053		PREPREG	4.000		
		VT47-106		0.053	0.053		PREPREG	4.000		
3		VT-47 4, 5, 6		0.018	0.035		Core	4.600		
4			VT-47		0.203	0.203		Core	4.120	
			VT-47		0.018	0.018		Core	4.120	
5		VT47-2113		0.096	0.096		PREPREG	4.000		
			VT-47		0.018	0.018		Core	4.120	
6		VT-47		0.102	0.102		Core	4.120		
			VT-47		0.018	0.018		Core	4.120	
7	VT47-106		0.053	0.053		PREPREG	4.000			
		VT47-106		0.053	0.053		PREPREG	4.000		
		VT-47		0.018	0.018		Core	4.120		
8	VT-47		0.102	0.102		Core	4.120			
		VT-47		0.018	0.018		Core	4.120		
9	VT47-2113		0.096	0.096		PREPREG	4.000			
		VT-47		0.018	0.018		Core	4.600		
10	VT-47 7, 8, 9		0.203	0.203		Core	4.600			
		VT-47		0.018	0.035		Core	4.600		
		VT47-106		0.053	0.053		PREPREG	4.000		
		VT47-106		0.053	0.053		PREPREG	4.000		
11	Foil		0.009	0.032		Foil		0		
		VT47-1080		0.075	0.075		PREPREG	4.000		
12	Foil 10, 11, 12		0.012	0.035		Foil		0		
		Soldermask				0.020	SolderMask	4.100	10	

Impedance ID	Structure Name	Structure Image	Impedance Signal Layer	Ref. Plane 1 in Layer	Ref. Plane 2 in Layer	Lower Trace Width (W1)	Trace Separation (S1)	Ground Strip Separation (D1)	Target Impedance	Calculated Impedance	Tol (+/- %)
1	Coated Microstrip 1B		1	2	0	0.093	0.000	0.000	55.000	55.060	10.000
2	Edge Coupled Coated Microstrip 1B		1	2	0	0.101	0.114	0.000	90.000	90.060	10.000
3	Edge Coupled Coated Microstrip 1B		1	2	0	0.090	0.160	0.000	100.000	100.300	10.000
4	Offset Stripline 1B1A		3	2	4	0.080	0.000	0.000	55.000	53.620	10.000

StackName: iMX6_Rex_V111_PCB_12L_VT47_mv	Version: 1	Revision:	Modification:	Date of Revision:	Editor
Date: 31/10/2013	Associated Documents:				
Author: DM					
Department: IDS					
Site: Tewkesbury					

Impedance ID	Structure Name	Structure Image	Impedance Signal Layer	Ref. Plane 1 in Layer	Ref. Plane 2 in Layer	Lower Trace Width (W1)	Trace Separation (S1)	Ground Strip Separation (D1)	Target Impedance	Calculated Impedance	Tol (+/- %)
5	Edge Coupled Offset Stripline 1B1A		3	2	4	0.085	0.115	0.000	90.000	88.390	10.000
6	Edge Coupled Offset Stripline 1B1A		3	2	4	0.085	0.195	0.000	100.000	98.390	10.000
7	Offset Stripline 1B1A		10	9	11	0.080	0.000	0.000	55.000	53.620	10.000
8	Edge Coupled Offset Stripline 1B1A		10	9	11	0.085	0.115	0.000	90.000	88.390	10.000
9	Edge Coupled Offset Stripline 1B1A		10	9	11	0.085	0.195	0.000	100.000	98.390	10.000
10	Coated Microstrip 1B		12	11	0	0.093	0.000	0.000	55.000	55.060	10.000
11	Edge Coupled Coated Microstrip 1B		12	11	0	0.101	0.114	0.000	90.000	90.060	10.000
12	Edge Coupled Coated Microstrip 1B		12	11	0	0.090	0.160	0.000	100.000	100.300	10.000

Drill Image	1st Layer	2nd Layer	Drill Type	Minimum Size	Fill Type	Data Filenames
	1	12	Mechanical PTH	0.000	None	
	1	2	Laser PTH	0.100	None	
	2	3	Laser PTH	0.100	None	
	12	11	Laser PTH	0.100	None	
	11	10	Laser PTH	0.100	None	


StackName: iMX6_Rex_V111_PCB_12L_VT47_mv	Version: 1	Revision:	Modification:	Date of Revision:	Editor
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Drill Image	1st Layer	2nd Layer	Drill Type	Minimum Size	Fill Type	Data Filenames
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3 10 Mechanical PTH 0.200 None

Notes

StackName: iMX6_Rex_V111_PCB_12L_VT47_mv	Version: 1	Revision:	Modification:	Date of Revision:	Editor	Page 3/3	
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